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(12) **United States Design Patent**  
**Otsuka et al.**

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(54) **SEMICONDUCTOR DEVICE**

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(\*\*) Term: **14 Years**

(21) Appl. No.: **29/440,819**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/110, 182; 257/678, 690; 361/713,  
361/679.01, 728, 736, 775, 760, 761, 820;  
324/754, 755, 756; 174/250, 253;  
438/64, 65

See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

5,347,160 A \* 9/1994 Sutrina ..... 257/698  
D357,672 S \* 4/1995 Terasawa et al. .... D13/182  
D396,847 S \* 8/1998 Nakayama et al. .... D13/182  
D441,726 S \* 5/2001 Sofue et al. .... D13/182

D441,727 S \* 5/2001 Sekimoto ..... D13/182  
D448,739 S \* 10/2001 Iwasaki et al. .... D13/182  
6,300,685 B1 \* 10/2001 Hasegawa et al. .... 257/780  
6,330,165 B1 \* 12/2001 Kohjiro et al. .... 361/760  
D457,146 S \* 5/2002 Yamamoto et al. .... D13/182  
D459,316 S \* 6/2002 Fukumoto et al. .... D13/182  
D465,773 S \* 11/2002 Fukumoto et al. .... D13/182  
D470,825 S \* 2/2003 Iwasaki et al. .... D13/182  
D472,530 S \* 4/2003 Iwasaki et al. .... D13/182  
D475,355 S \* 6/2003 Hori et al. .... D13/182  
D476,959 S \* 7/2003 Yamada et al. .... D13/182  
D476,962 S \* 7/2003 Yoshihira et al. .... D13/182  
D480,371 S \* 10/2003 Fukuda et al. .... D13/182  
6,713,868 B2 \* 3/2004 Ueno ..... 257/730  
D502,151 S \* 2/2005 Standing ..... D13/182

(Continued)

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(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of a semiconductor device showing our new design;

FIG. 2 is a rear view thereof;

FIG. 3 is a right side view thereof;

FIG. 4 is a left side view thereof;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof;

FIG. 7 is a partially enlarged view thereof taken along lines VII-VII in FIG. 2;

FIG. 8 is a partially enlarged view thereof taken along lines VIII-VIII in FIG. 4;

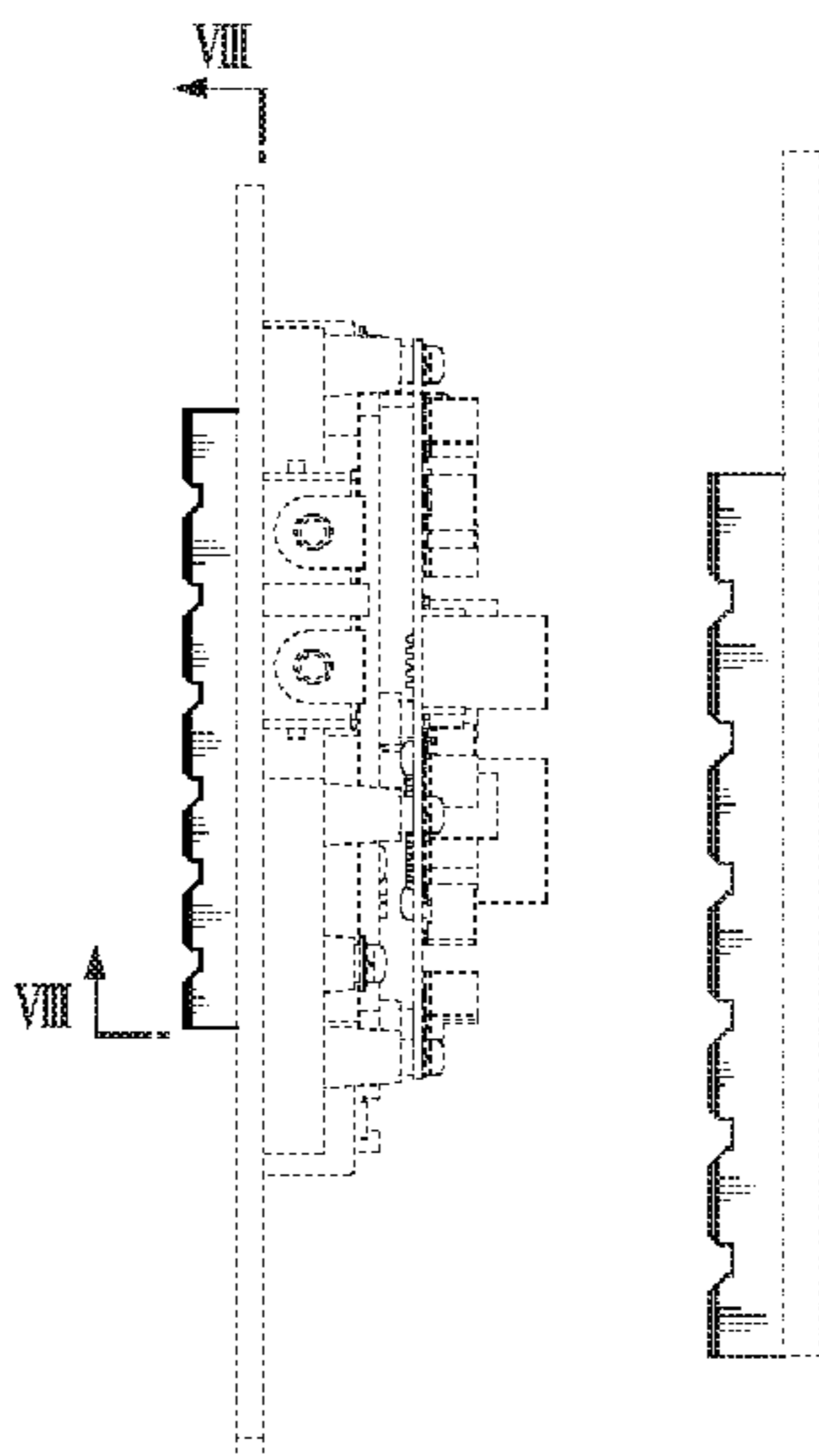
FIG. 9 is a partially enlarged view thereof taken along lines IX-IX in FIG. 5;

FIG. 10 is a front perspective view thereof; and,

FIG. 11 is a rear perspective view thereof.

The broken lines depict environmental subject matter only and form no part of the claimed design.

**1 Claim, 8 Drawing Sheets**



(56)

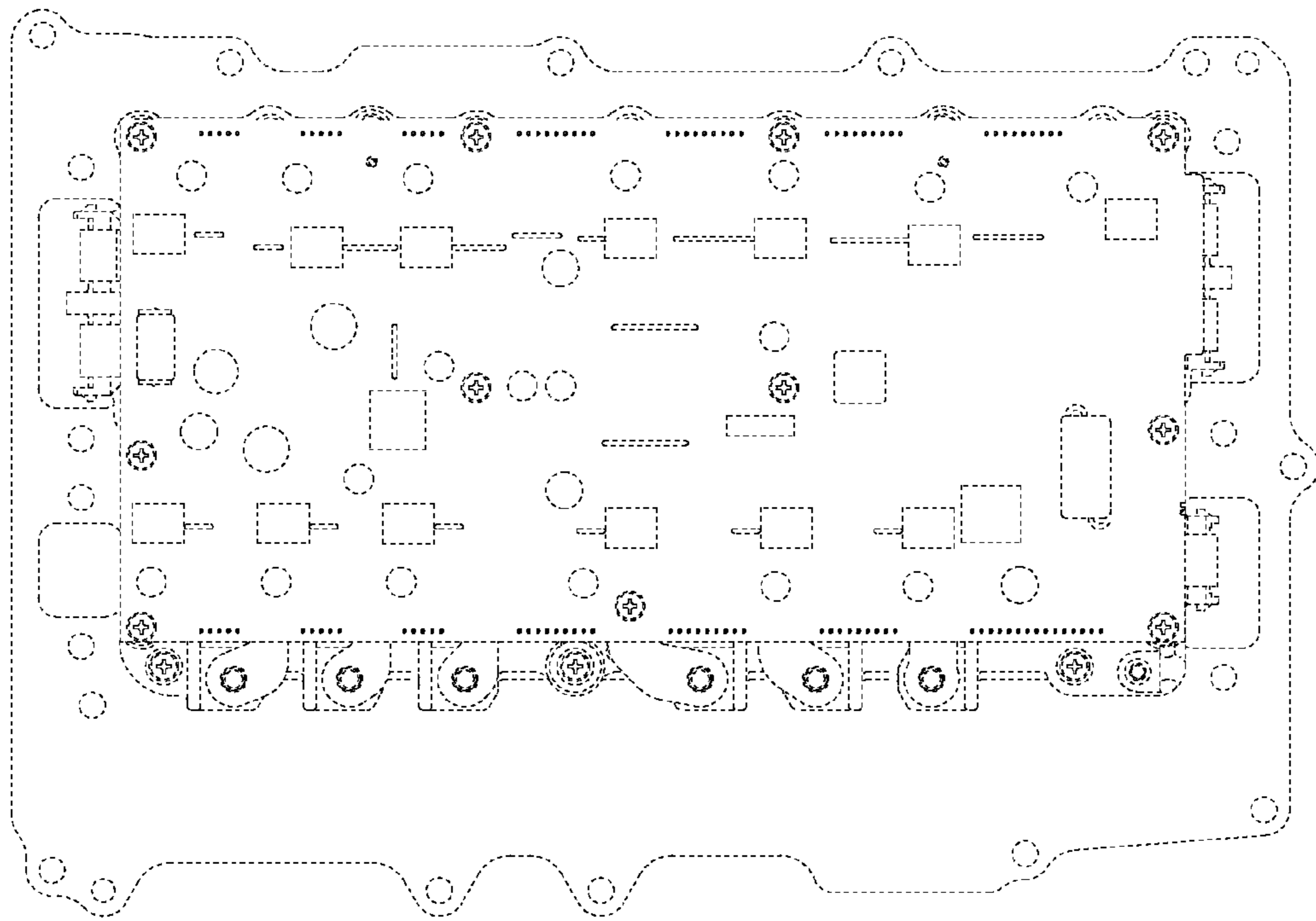
**References Cited**

U.S. PATENT DOCUMENTS

D504,405 S \* 4/2005 Kawaguchi et al. .... D13/182  
D505,399 S \* 5/2005 Yoshida et al. .... D13/182  
D507,248 S \* 7/2005 Hisaishi et al. .... D13/182  
D507,545 S \* 7/2005 Nakamura et al. .... D13/182  
D508,682 S \* 8/2005 Yamada et al. .... D13/182  
D521,952 S \* 5/2006 Yamada et al. .... D13/182

D525,215 S \* 7/2006 Hisaishi et al. .... D13/182  
D539,761 S \* 4/2007 Takahashi et al. .... D13/182  
D548,203 S \* 8/2007 Takahashi et al. .... D13/182  
D587,662 S \* 3/2009 Soutome et al. .... D13/182  
D589,012 S \* 3/2009 Soyano et al. .... D13/182  
D653,633 S \* 2/2012 Soyano .... D13/182  
D653,634 S \* 2/2012 Soyano .... D13/182  
2004/0016993 A1 \* 1/2004 Ham et al. .... 257/666

\* cited by examiner



**FIG. 1**

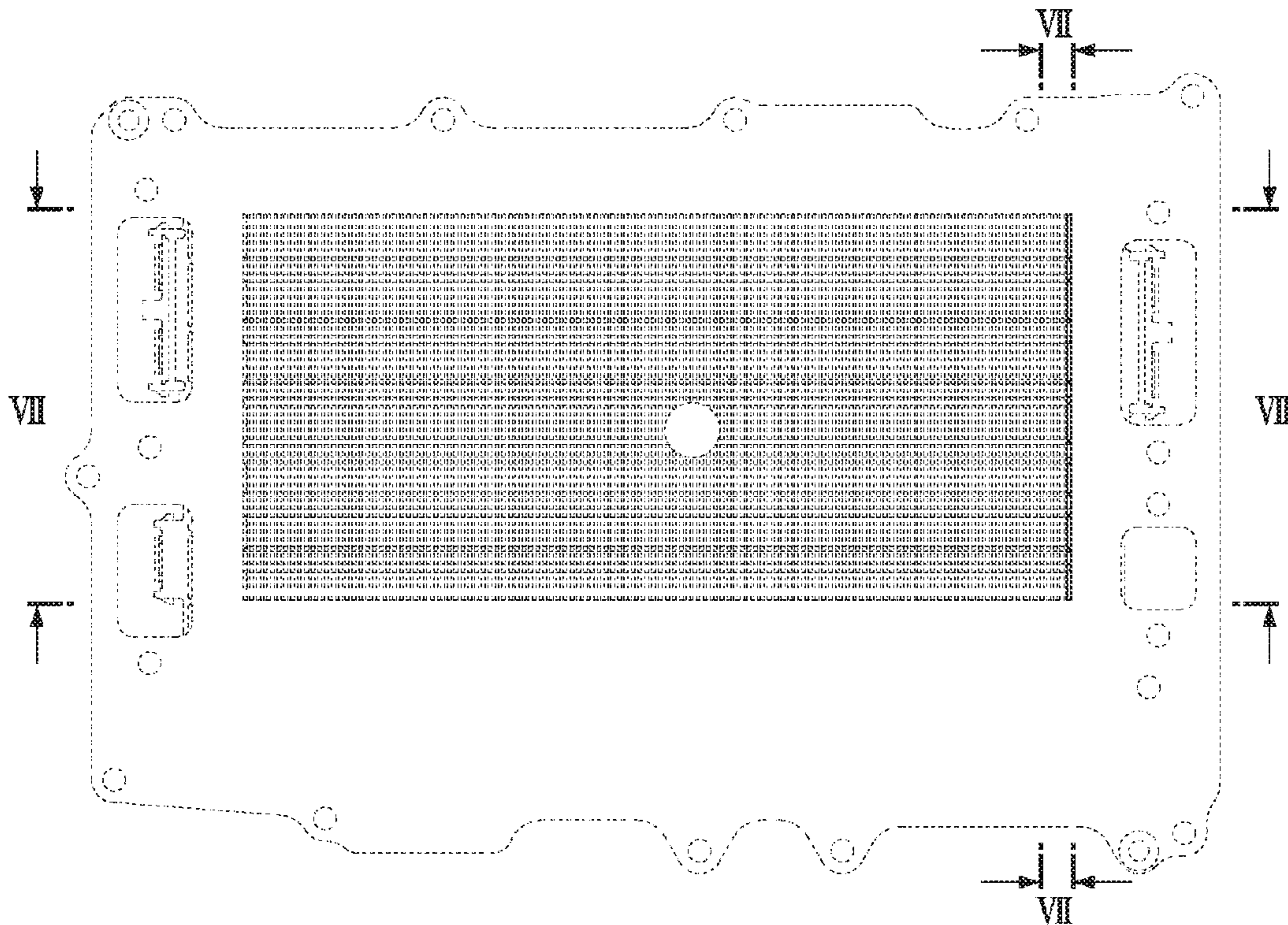


FIG. 2

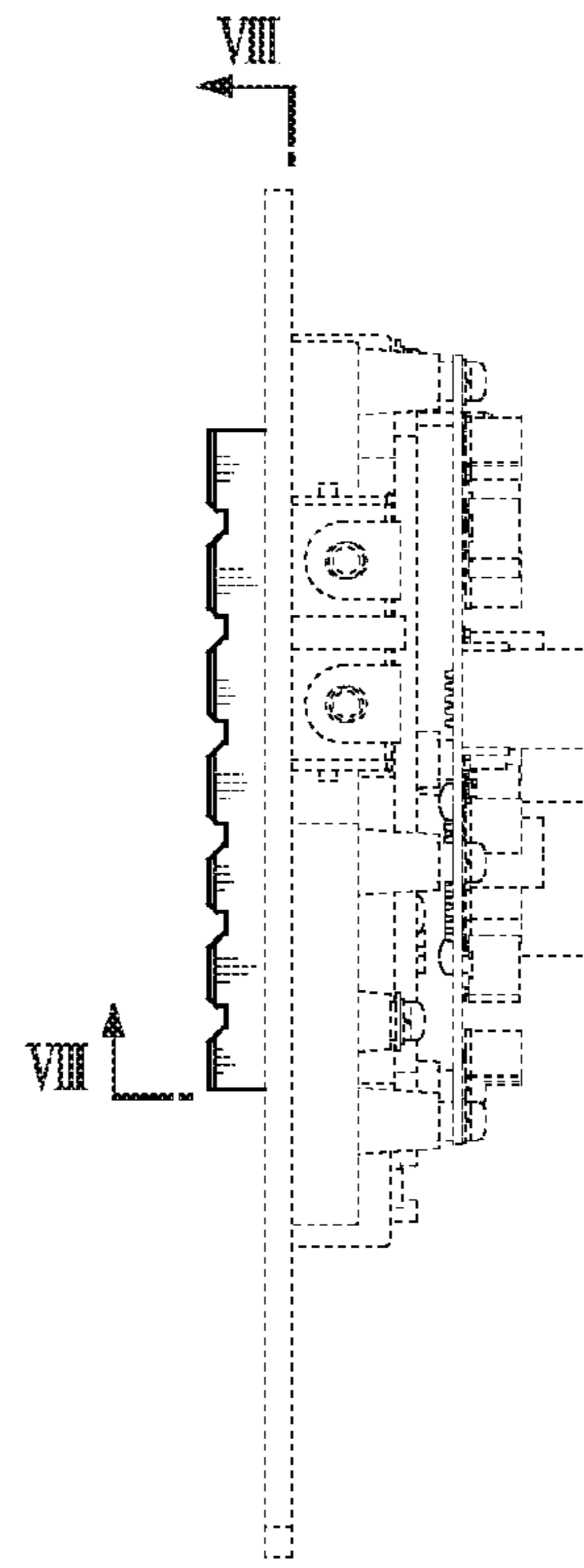
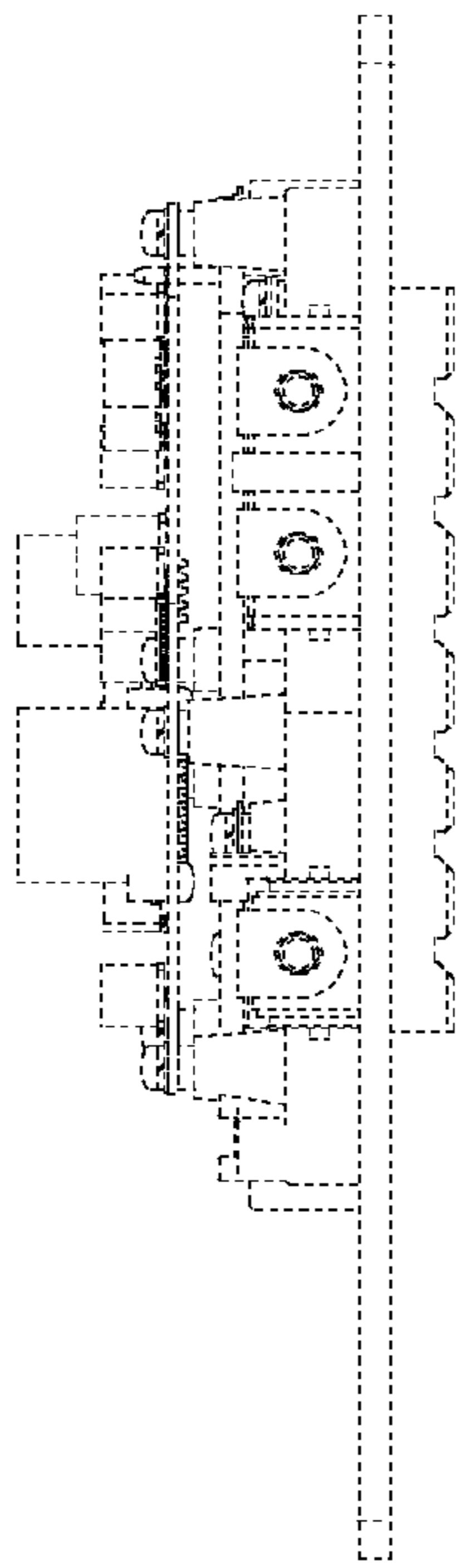
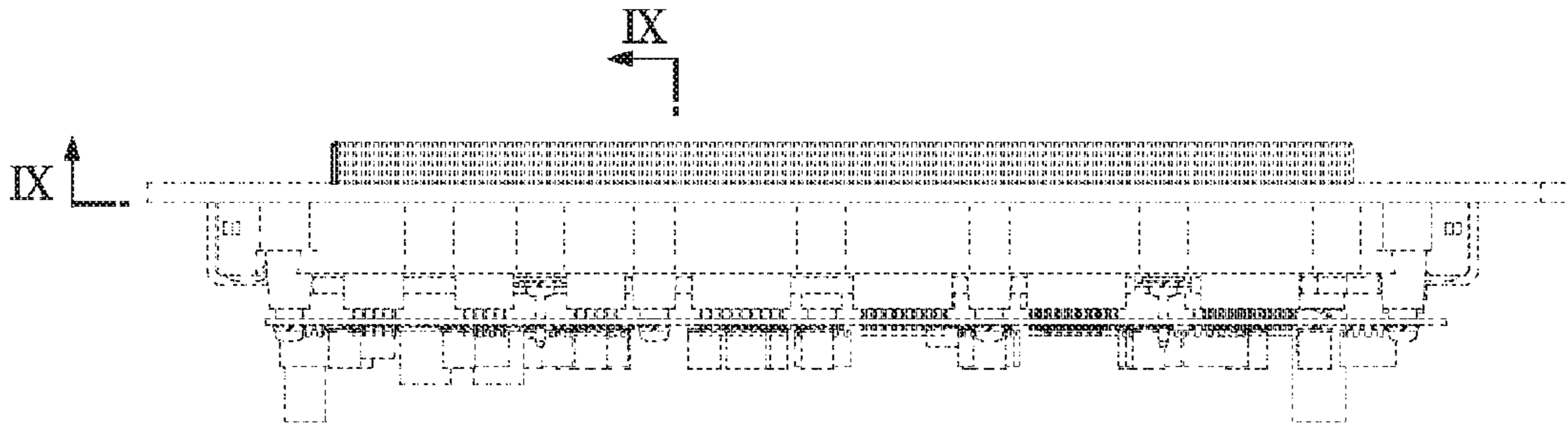
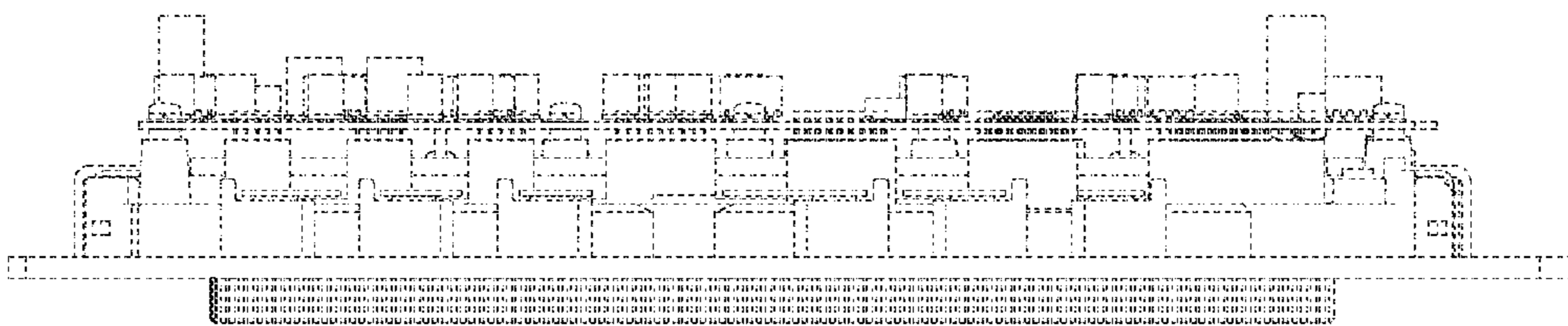


FIG. 3

FIG. 4



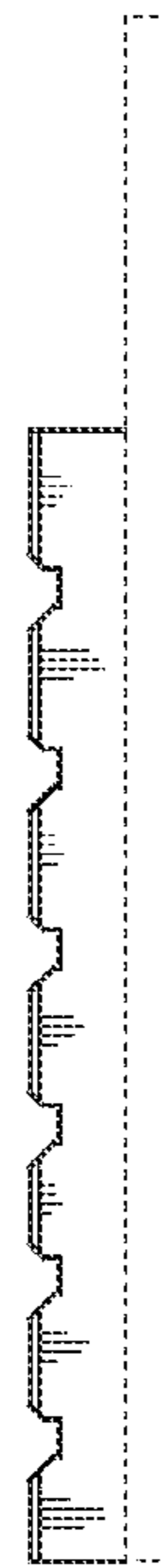
**FIG. 5**



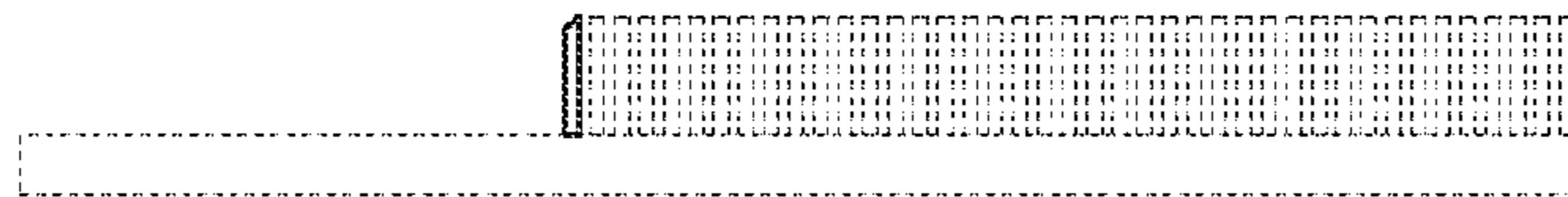
**FIG. 6**



**FIG. 7**

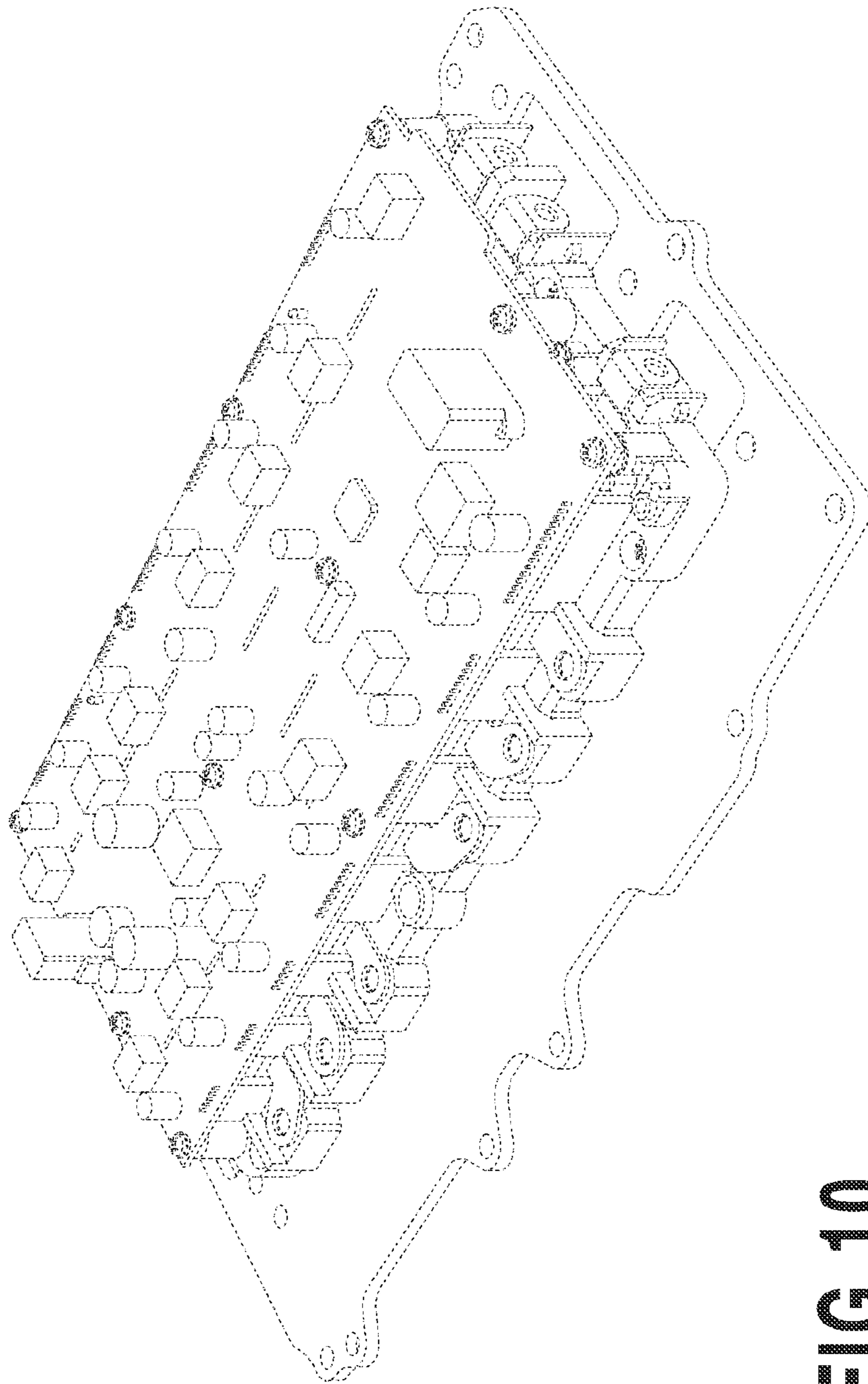


**FIG. 8**

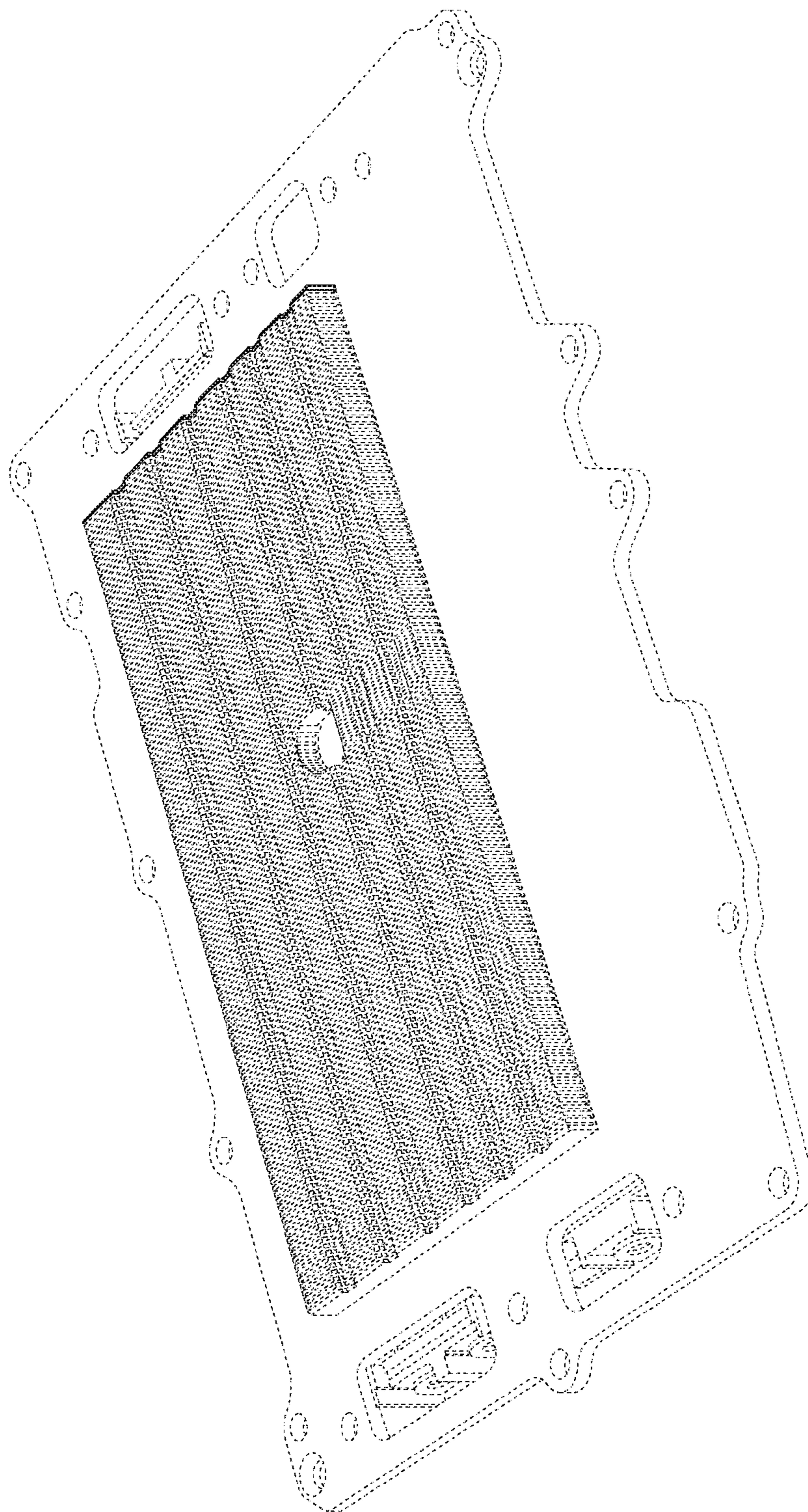


**FIG. 9**





**FIG.10**



**FIG. 11**